

IN THE CLAIMS

Please amend the claims to read as follows:

Listing of Claims

1. (Currently Amended) A semiconductor device layout inspection method for inspecting formation defects that will occur in wires of a chip layout, wherein the wire formation defects are detected by checking ~~the ratio between the layout of~~ the concentration of contact holes in said wires and of the chip layout ~~of said wires~~.

2. (Original) The semiconductor device layout inspection method according to claim 1, wherein the layout of wires where wire formation defects have been detected is corrected.

3-17. (Canceled).

18. (New) The semiconductor device layout inspection method according to claim 1, wherein the concentration is a total area concentration.

19. (New) The semiconductor device layout inspection method according to claim 1, wherein the concentration is a total number concentration.